



Material Content Data Sheet



Sales Product Name		ICE3A1565		Issued		29. August 2013		
MA#		MA001054986						
Package		PG-DIP-8-6		Weight*		538.23 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.127	0.77	0.77	7668	7668
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		99	
	non noble metal	zinc	7440-66-6	0.213	0.04		396	
	non noble metal	iron	7439-89-6	4.266	0.79		7927	
wire	non noble metal	copper	7440-50-8	173.237	32.19	33.03	321866	330288
	noble metal	gold	7440-57-5	0.377	0.07	0.07	701	701
	encapsulation	organic material	carbon black	1333-86-4	1.731	0.32		3216
encapsulation	inorganic material	antimonytrioxide	1309-64-4	6.925	1.29		12866	
	plastics	brominated resin	-	6.925	1.29		12866	
	plastics	epoxy resin	-	39.818	7.40		73979	
	inorganic material	silicondioxide	60676-86-0	290.843	54.02	64.32	540371	643298
leadfinish	non noble metal	tin	7440-31-5	7.496	1.39	1.39	13927	13927
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1488	1488
glue	plastics	epoxy resin	-	0.248	0.05		460	
	noble metal	silver	7440-22-4	1.168	0.22	0.27	2170	2630
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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